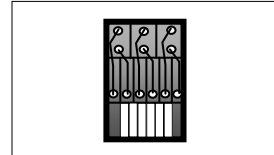
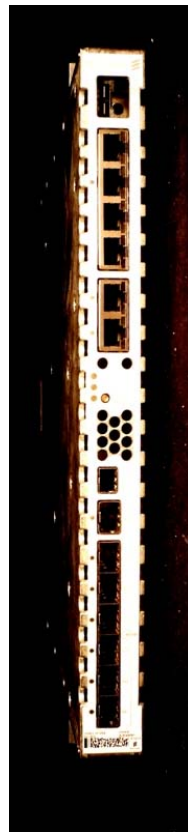


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**Ericsson LTE Baseband Unit
KDU 137 533/4 R1F
Model DUL 20 01**

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